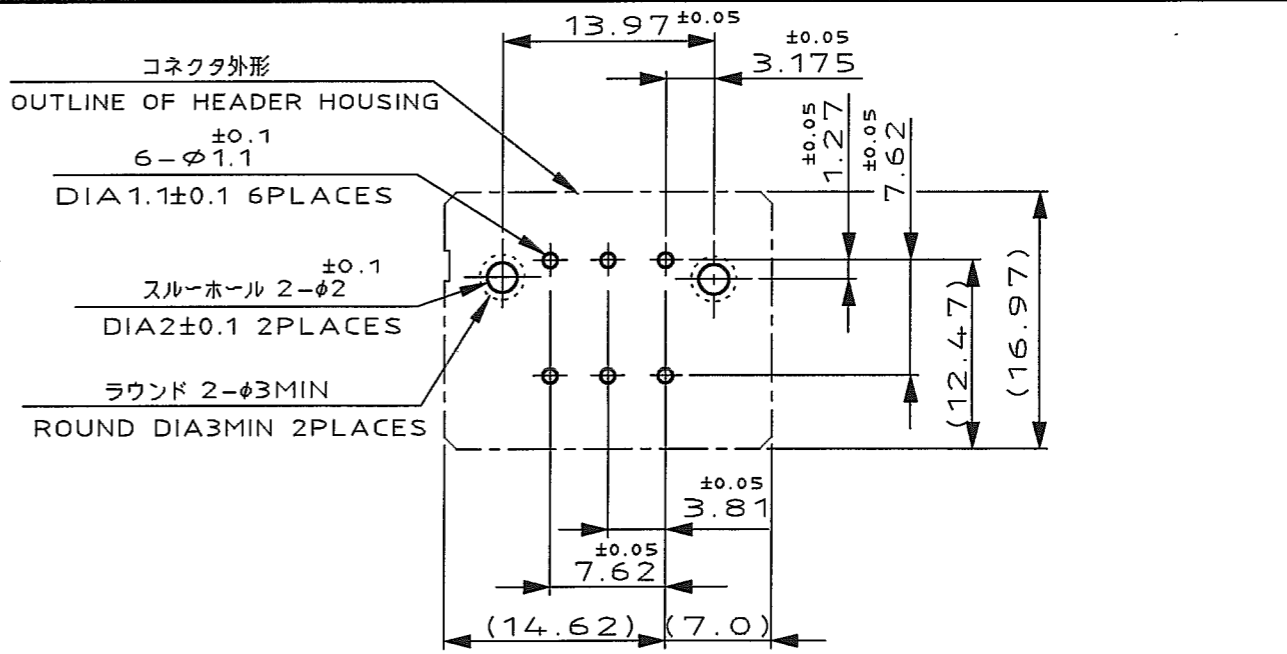
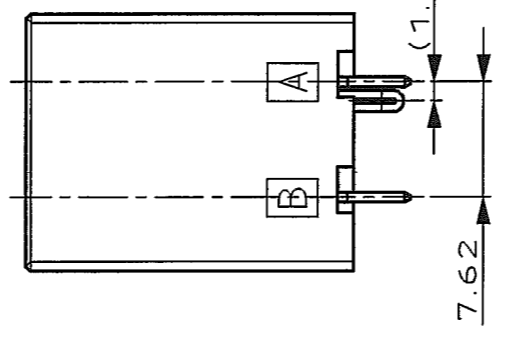
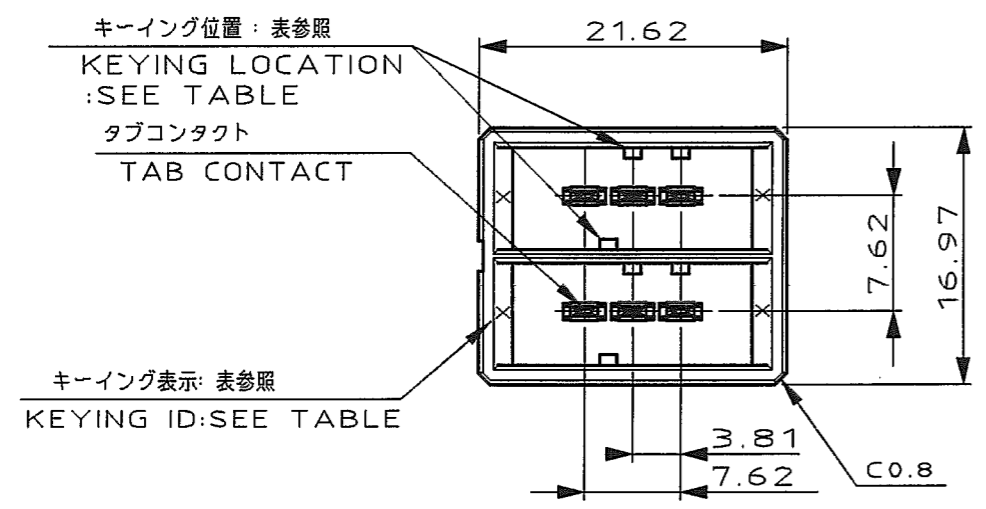
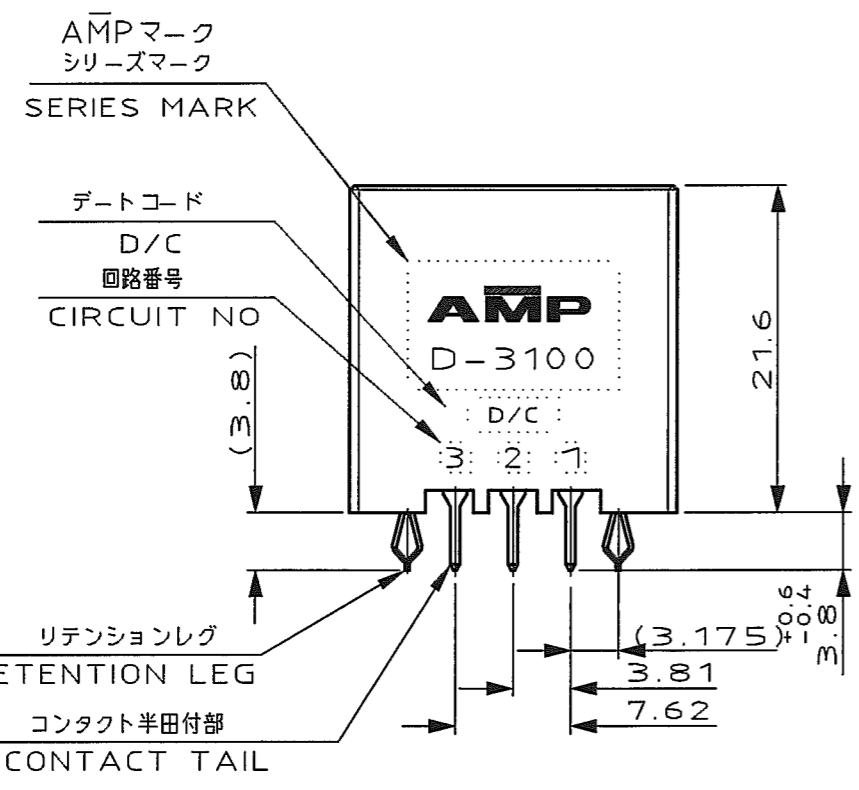


NUMBER 178141
 METRIC
 DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT
 PRINT DIST



推奨基板取付け穴寸法
 PC 基板厚: 1.6±0.1
 (非累積公差)
 (コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
 PC BOARD THICKNESS: 1.6±0.1
 (NOT ACCUMULATE TOLERANCE)
 (CONNECTOR MOUNT SIDE)



NOTES

- MATERIAL: HOUSING: GLASS FILED THERMO PLASTIC, POLYESTER (94V-0), COLOR: BLACK
 CONTACT: COPPER ALLOY
 RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 0.76μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂 (94V-0), 色: 黒
 コネクタ: 銅合金
 リテンションレグ: 銅合金
- めっき: コンタクト: 全面Ni下地
 接触部: 0.38μm MIN金めっき
- めっき: コンタクト: 全面Ni下地
 接触部: 0.76μm MIN金めっき
- めっき: コンタクト: 全面Ni下地
 接触部: 2.0 μm MINスズめっき
- めっき: リテンションレグとコンタクト半田付部
 ニッケル下地の上に半田めっき
- めっき: リテンションレグとコンタクト半田付部
 ニッケル下地の上にスズめっき

A ROW		X	Y	△6	△4	3-178141-5
B ROW				△6	△3	3-178141-3
A ROW		X	X	△6	△4	1-178141-5
B ROW				△6	△3	1-178141-3
				△6	△2	1-178141-2
KEYING LOCATION				A ROW KEYING	B ROW KEYING	製品番号 PART NO.



WIRE RANGE	INSULATION DIA	NAME	DYNAMIC D-3100 3.81X7.62PITCH(V) 6 POS.HDR CONN.ASS'Y		
mm²(AWG -)	mmφ		一般公差 (GENERAL TOLERANCE)	SIZE	LOC
			100% ±0.3	A3	J
MATERIAL SEE NOTE 注記参照	FINISH SEE NOTE 注記参照		100% 300% ±0.4	SCALE	REV.
			300% 100% ±0.45	2-1	E1
DR. 19 APR 94 N. Matsubara	DE. 19 APR 94 N. Matsubara		角度 ±3'	NUMBER	SHEET
CHK. 20 APR 94 S. MANABE	APP. 20 APR 94 S. MANABE			©-178141	1 OF 1

E1	REVISED PER ECO-11-005030	RK	HMR	28MAR 11
LTR	REVISION RECORD	DR	CHK	DATE

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